

# PESDxUSB3B/C series

ESD protection for differential data lines

Rev. 2 — 29 January 2019

Product data sheet

## 1. Product profile

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### 1.1. General description

ElectroStatic Discharge (ESD) protection for one, two and three differential channels.

The devices are footprint compatible to PCMFxUSB3B/C common mode filters with ESD protection.

Diodes provide protection to downstream components from ESD voltages up to  $\pm 20$  kV on each signal line.

**Table 1. Product overview**

Type number	Number of channels	Package Name
PESD1USB3B/C	1	WLCSP5
PESD2USB3B/C	2	WLCSP10
PESD3USB3B/C	3	WLCSP15

### 1.2. Features and benefits

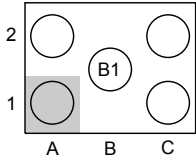
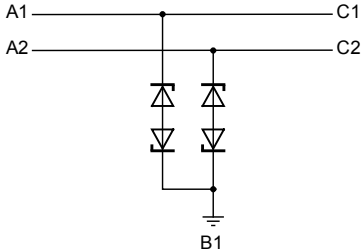
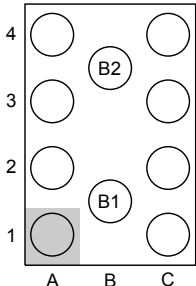
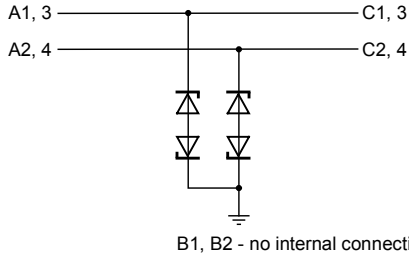
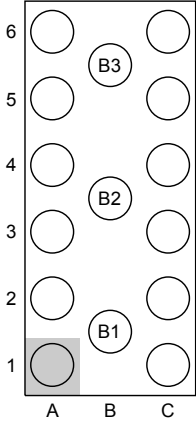
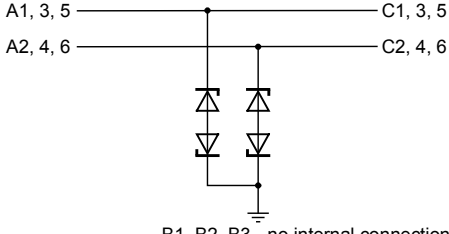
- Allows switching between PCMFxUSB3B/C common mode filters with ESD protection and PESDxUSB3B/C ESD protection in the same footprint
- TrEOS protection process for very high system-level ESD robustness: superior protection of sensitive Systems on Chips (SoCs)
- ESD protection for one, two and three differential channels up to  $\pm 20$  kV contact discharge according to IEC 61000-4-2
- Industry-standard WLCSP5, 10 and 15 packages for smallest footprint
- Bidirectional for audio line option

### 1.3. Applications

- Smartphone, cellular and cordless phone
- USB3.2, USB2.0, HDMI2.0, HDMI1.4
- General-purpose downstream ESD protection for differential data lines
- Tablet PC and Mobile Internet Device (MID)
- MIPI D-PHY as used in Camera Serial Interface (CSI) and Display Serial Interface (DSI)

## 2. Pinning information

Table 2. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
<b>PESD1USB3B/C (WLCSP5_2-1-2)</b>				
A1	CH1_IN+	channel 1+, external	 <p>Transparent top view <b>WLCSP5_2-1-2</b></p>	 <p>aaa-028532</p>
A2	CH1_IN-	channel 1-, external		
B1	GND_CH1	ground channel 1		
C1	CH1_OUT+	channel 1+, internal		
C2	CH1_OUT-	channel 1-, internal		
<b>PESD2USB3B/C (WLCSP10_4-2-4)</b>				
A1	CH1_IN+	channel 1+, external	 <p>Transparent top view <b>WLCSP10_4-2-4</b></p>	 <p>B1, B2 - no internal connection aaa-028533</p>
A2	CH1_IN-	channel 1-, external		
A3	CH2_IN+	channel 2+, external		
A4	CH2_IN-	channel 2-, external		
B1	GND_CH1	ground channel 1		
B2	GND_CH2	ground channel 2		
C1	CH1_OUT+	channel 1+, internal		
C2	CH1_OUT-	channel 1-, internal		
C3	CH2_OUT+	channel 2+, internal		
C4	CH2_OUT-	channel 2-, internal		
<b>PESD3USB3B/C (WLCSP15_6-3-6)</b>				
A1	CH1_IN+	channel 1+, external	 <p>Transparent top view <b>WLCSP15_6-3-6</b></p>	 <p>B1, B2, B3 - no internal connection aaa-028534</p>
A2	CH1_IN-	channel 1-, external		
A3	CH2_IN+	channel 2+, external		
A4	CH2_IN-	channel 2-, external		
A5	CH3_IN+	channel 3+, external		
A6	CH3_IN-	channel 3-, external		
B1	GND_CH1	ground channel 1		
B2	GND_CH2	ground channel 2		
B3	GND_CH3	ground channel 3		
C1	CH1_OUT+	channel 1+, internal		
C2	CH1_OUT-	channel 1-, internal		
C3	CH2_OUT+	channel 2+, internal		
C4	CH2_OUT-	channel 2-, internal		
C5	CH3_OUT+	channel 3+, internal		
C6	CH3_OUT-	channel 3-, internal		

### 3. Ordering information

**Table 3. Ordering information**

Type number	Package	
	Name	Description
PESD1USB3B/C	WLCSP5	wafer level chip-size package; 5 bumps (2-1-2)
PESD2USB3B/C	WLCSP10	wafer level chip-size package; 10 bumps (4-2-4)
PESD3USB3B/C	WLCSP15	wafer level chip-size package; 15 bumps (6-3-6)

### 4. Marking

**Table 4. Marking codes**

Type number	Marking code
PESD1USB3B/C	PD1B
PESD2USB3B/C	PD2B
PESD3USB3B/C	PD3B

### 5. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_I$	input voltage		-4	4	V	
$V_{ESD}$	electrostatic discharge voltage	IEC 61000-4-2, level 4; all input pins to ground				
		• contact discharge	-20	20	kV	
		• air discharge	-20	20	kV	
		IEC 61000-4-2, level 4; all output pins to ground				
		• contact discharge	-2	2	kV	
		• air discharge	-2	2	kV	
$I_{PPM}$	rated peak-pulse current	$t_p = 8/20 \mu s$	-9.5	9.5	A	
$T_{stg}$	storage temperature		-40	+125	°C	
$T_{amb}$	ambient temperature		-40	+125	°C	

## 6. Characteristics

### 6.1. Channel characteristics

**Table 6. Channel characteristics**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$C_d$	diode capacitance	$f = 1\text{ MHz}; V_l = 2.5\text{ V}$	[1] -	0.29	-	pF
$I_{RM}$	reverse leakage current	per line; $V_l = 5\text{ V}$	-	1	100	nA
$V_{BR}$	breakdown voltage	$I_R = 1\text{ mA}$	6	9	-	V
$V_F$	forward voltage	$I_F = 10\text{ mA}$	-	0.8	-	V
$R_{dyn}$	dynamic resistance	TLP	[2]			
		• positive transient	-	0.2	-	$\Omega$
		• negative transient	-	0.2	-	$\Omega$
		surge	[3]			
		• positive transient	-	0.2	-	$\Omega$
		• negative transient	-	0.2	-	$\Omega$

[1] This parameter is guaranteed by design.

[2] 100 ns Transmission Line Pulse (TLP); 50  $\Omega$ ; pulser at 70 to 90 ns.

[3] According to IEC 61000-4-5 (8/20  $\mu\text{s}$ ).

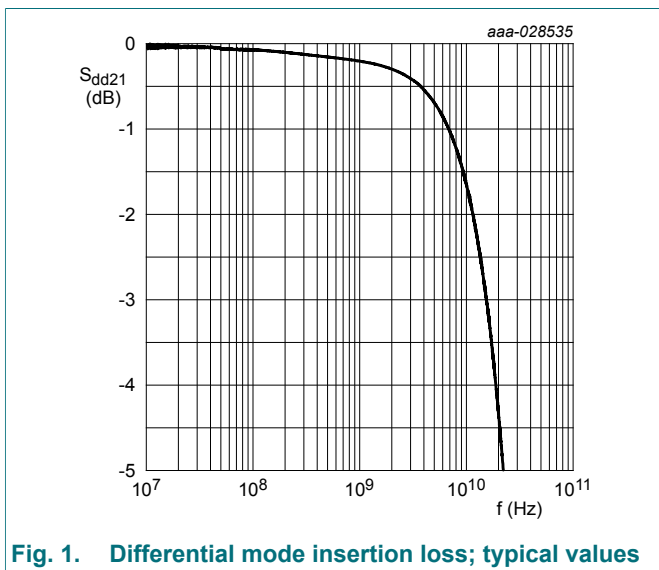
### 6.2. Frequency characteristics

**Table 7. Frequency characteristics**

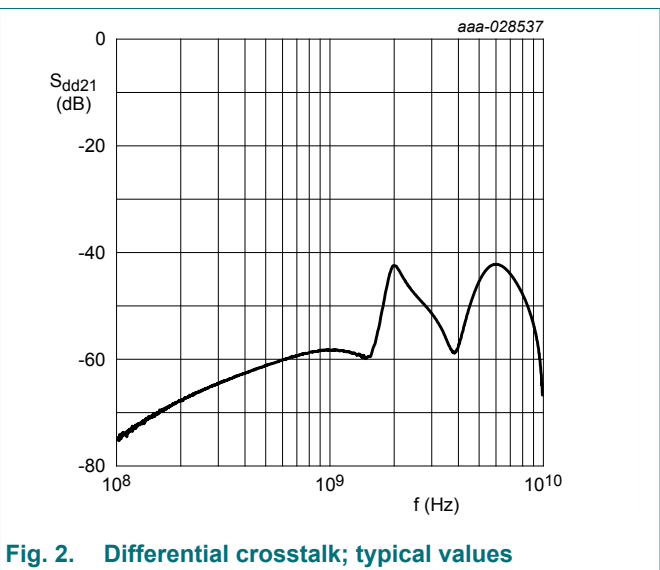
$T_{amb} = 25\text{ °C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Differential mode: <math>S_{dd21}</math></b>						
$f_{-3dB}$	cut-off frequency		[1] -	16.1	-	GHz

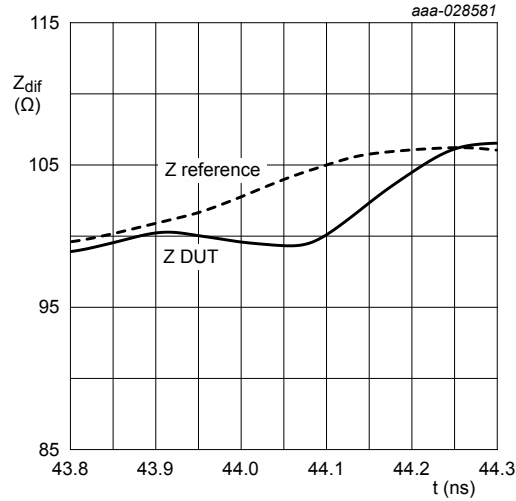
[1] Normalized to attenuation at 1 MHz.



**Fig. 1. Differential mode insertion loss; typical values**



**Fig. 2. Differential crosstalk; typical values**



$t_r = 200$  ps

Fig. 3. Differential Time Domain Reflectometer (TDR) plot; typical values

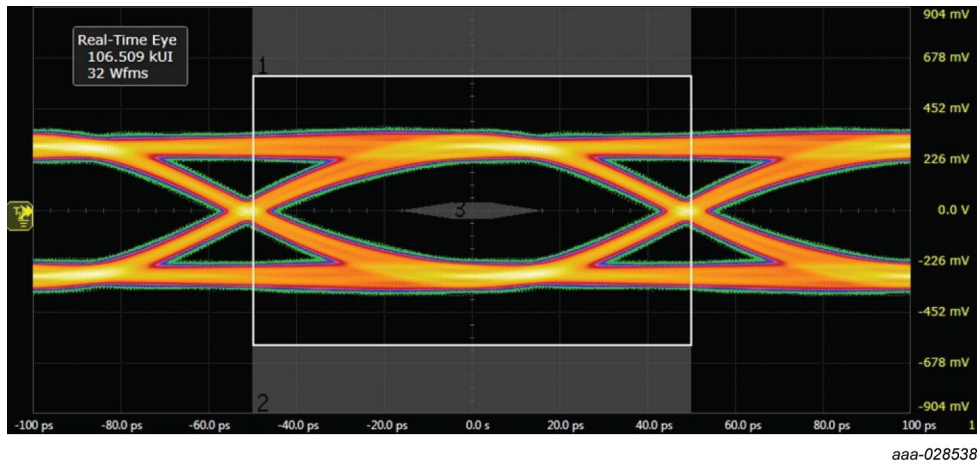


Fig. 4. USB 3.2 eye diagram 10 Gbps, test board with PCMFxUSB3B/C; typical values

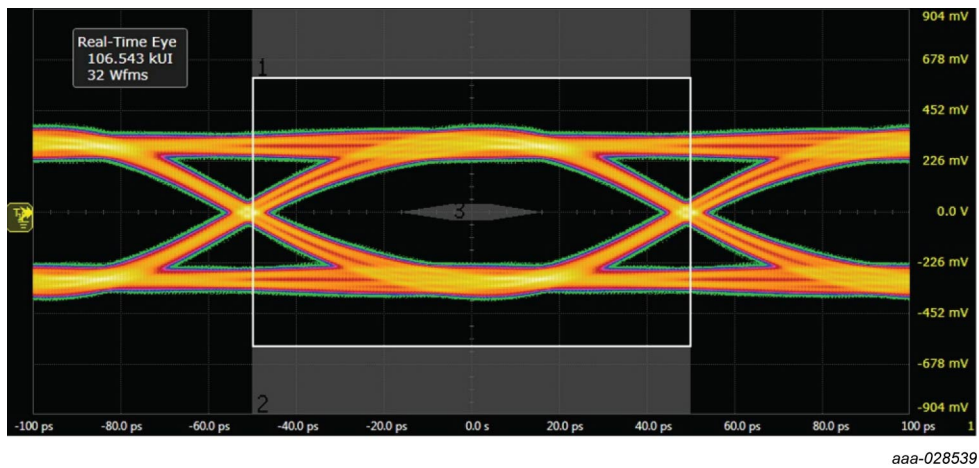


Fig. 5. USB 3.2 eye diagram 10 Gbps, test board without device; typical values

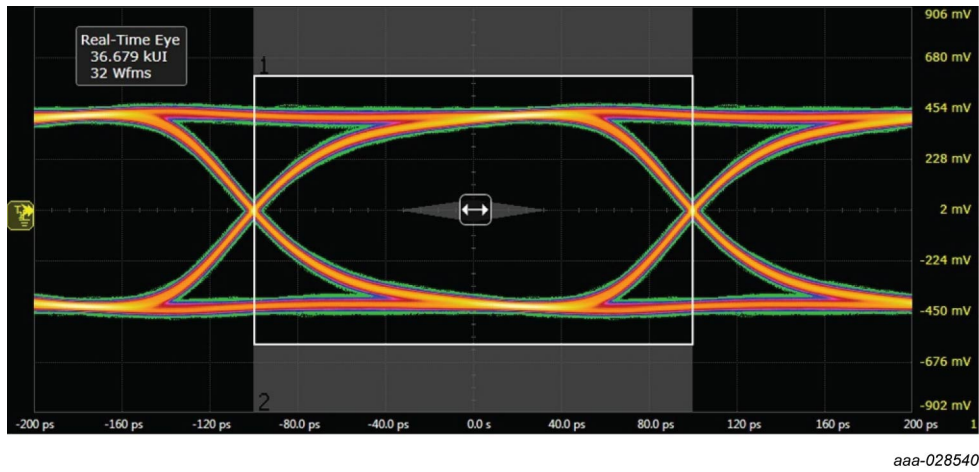


Fig. 6. USB 3.2 eye diagram 5 Gbps, test board with PCMFxUSB3B/C; typical values

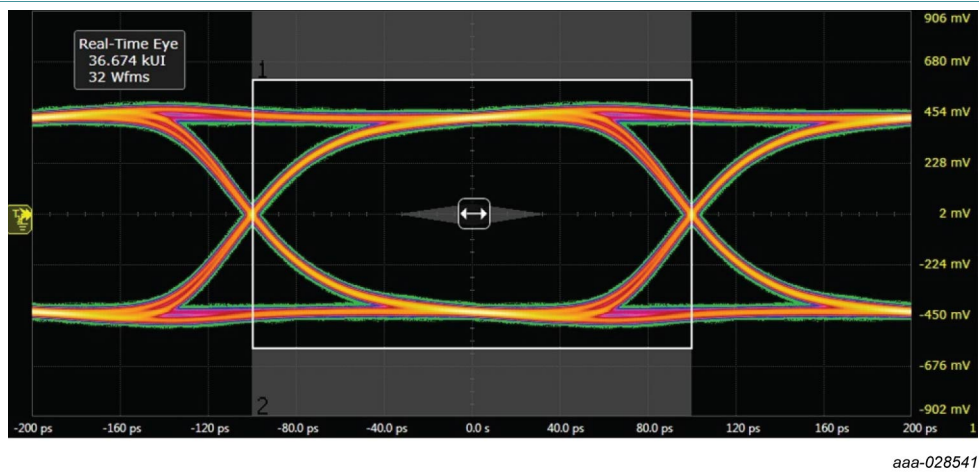
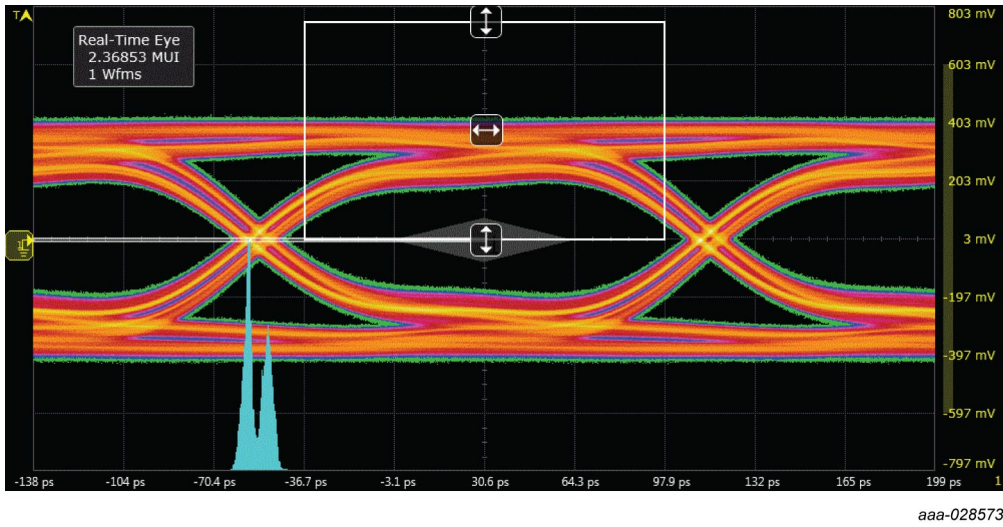
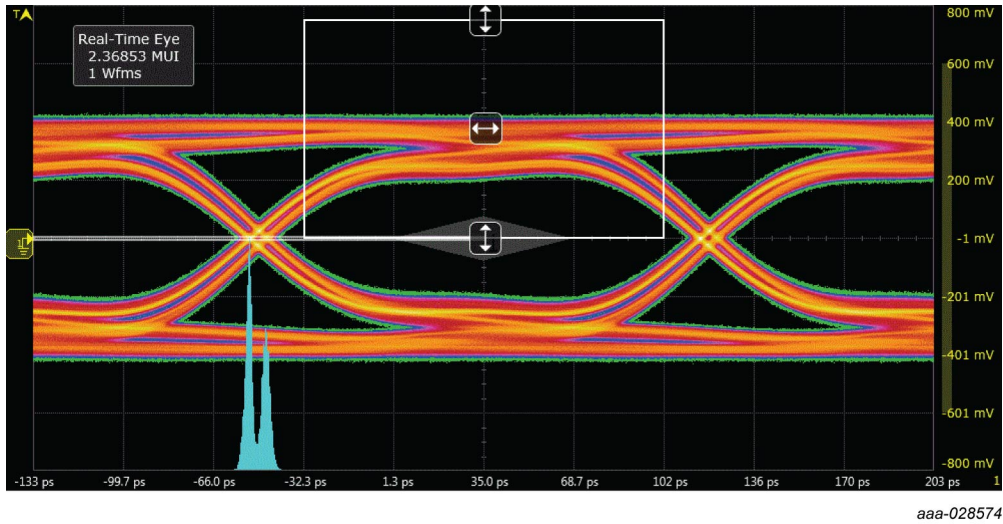


Fig. 7. USB 3.2 eye diagram 5 Gbps, test board without device; typical values



1080p, 6 Gbps

Fig. 8. HDMI 2.0 eye diagram TP1, test board with PCMFxUSB3B/C; typical values



1080p, 6 Gbps

Fig. 9. HDMI 2.0 eye diagram TP1, test board without device; typical values

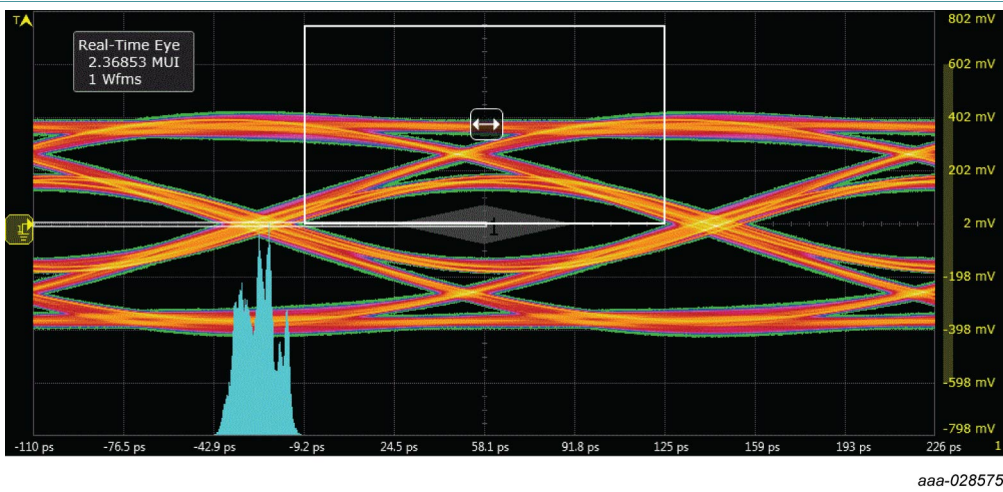
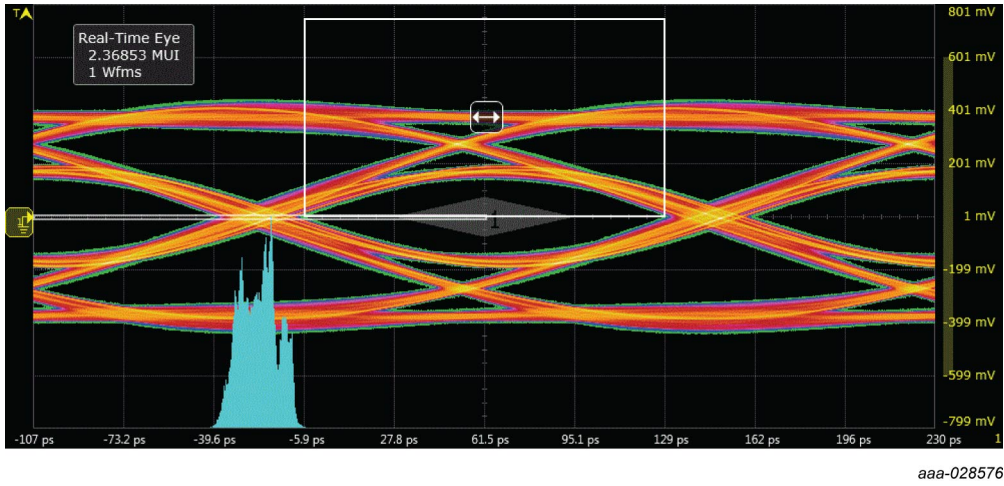
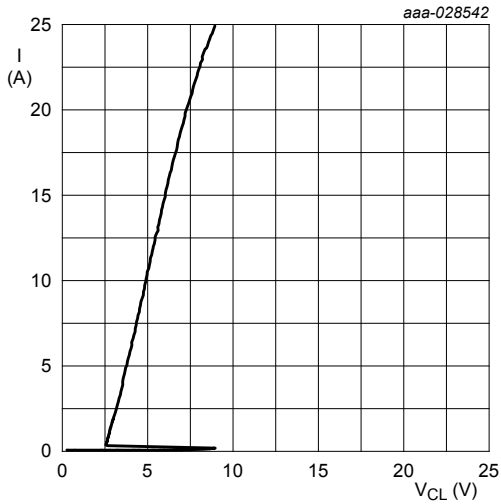


Fig. 10. HDMI 2.0 eye diagram TP2, test board with PCMFxUSB3B/C; typical values



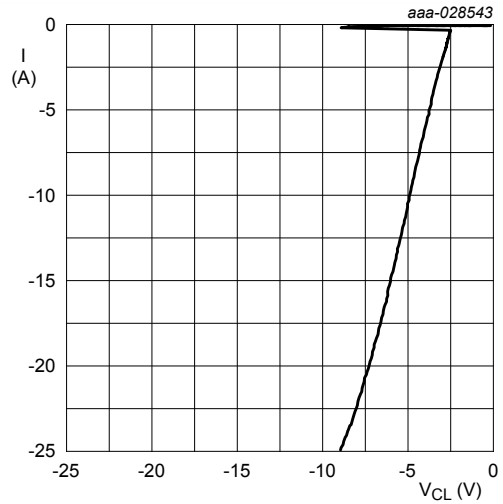
1080p, 6 Gbps

**Fig. 11. HDMI 2.0 eye diagram TP2, test board without device; typical values**



Transmission Line Pulse (TLP) = 100 ns;

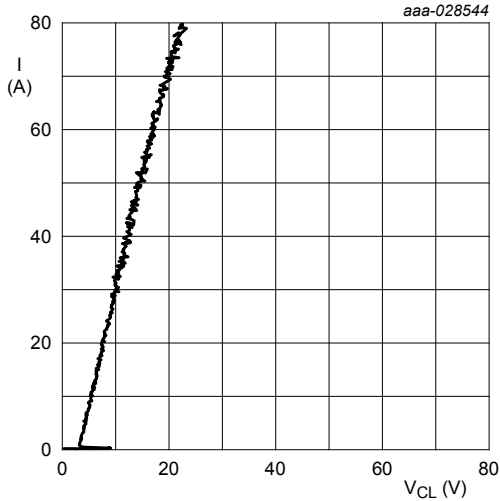
**Fig. 12. Dynamic resistance with positive clamping; typical values**



Transmission Line Pulse (TLP) = 100 ns;

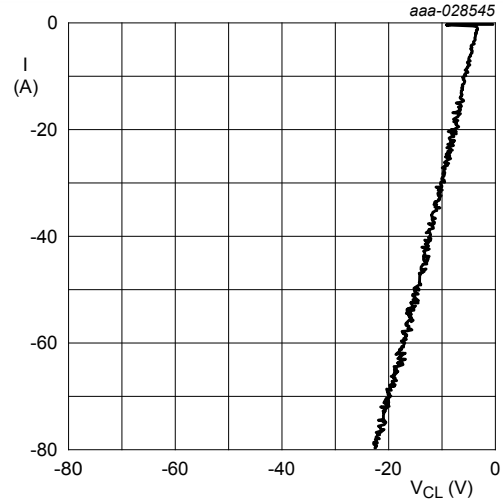
**Fig. 13. Dynamic resistance with negative clamping; typical values**





Transmission Line Pulse (TLP) = 5 ns

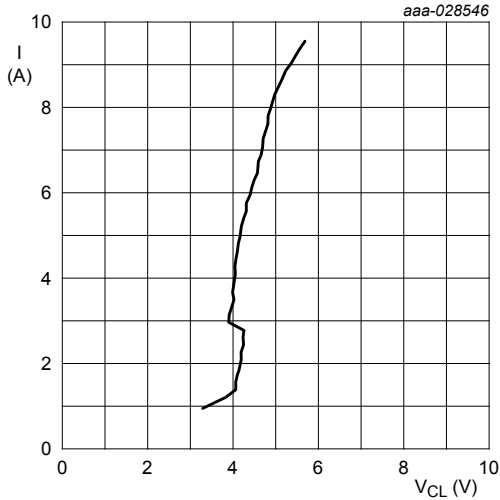
**Fig. 14. Dynamic resistance with positive clamping; typical values**



Transmission Line Pulse (TLP) = 5 ns

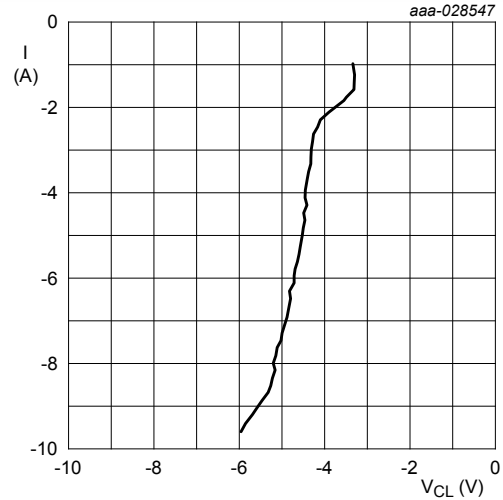
**Fig. 15. Dynamic resistance with negative clamping; typical values**

The device uses an advanced clamping structure showing a negative dynamic resistance. This snap-back behavior strongly reduces the clamping voltage to the system behind the ESD protection during an ESD event. Do not connect unlimited DC current sources to the data lines to avoid keeping the ESD protection device in snap-back state after exceeding breakdown voltage (due to an ESD pulse for instance).



IEC61000-4-5;  $t_p = 8/20 \mu s$ ; positive pulse

**Fig. 16. Dynamic resistance with positive clamping; typical values**



IEC61000-4-5;  $t_p = 8/20 \mu s$ ; negative pulse

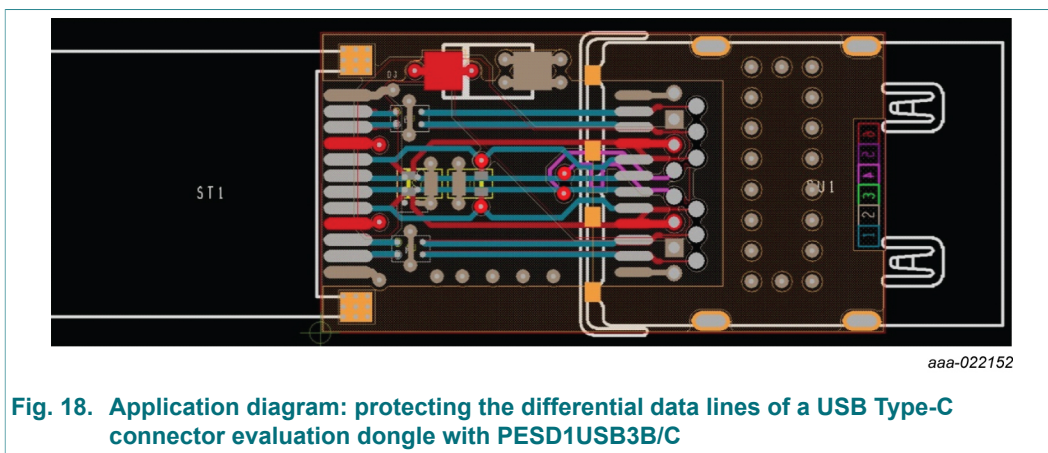
**Fig. 17. Dynamic resistance with negative clamping; typical values**

## 7. Application information

The device is designed to provide high-level ESD protection for differential high-speed data line pairs such as:

- USB 3.2
- HDMI 2.0
- Transition-Minimized Differential Signaling (TMDS)
- DisplayPort
- external Serial Advanced Technology Attachment (eSATA)
- Low Voltage Differential Signaling (LVDS)

When designing the Printed-Circuit Board (PCB), give careful consideration to impedance matching and signal coupling. Do not connect the protected signal lines to unlimited current sources like, for example, a battery.



**Fig. 18. Application diagram: protecting the differential data lines of a USB Type-C connector evaluation dongle with PESD1USB3B/C**

Since the SuperSpeed TX/RX lines are separated by GND or VBUS from the Hi-Speed lines, PESD1USB3B/C makes it easy to achieve same signal lengths, straight routing, and optimal positioning for ESD protection directly at the connector.

8. Package outline

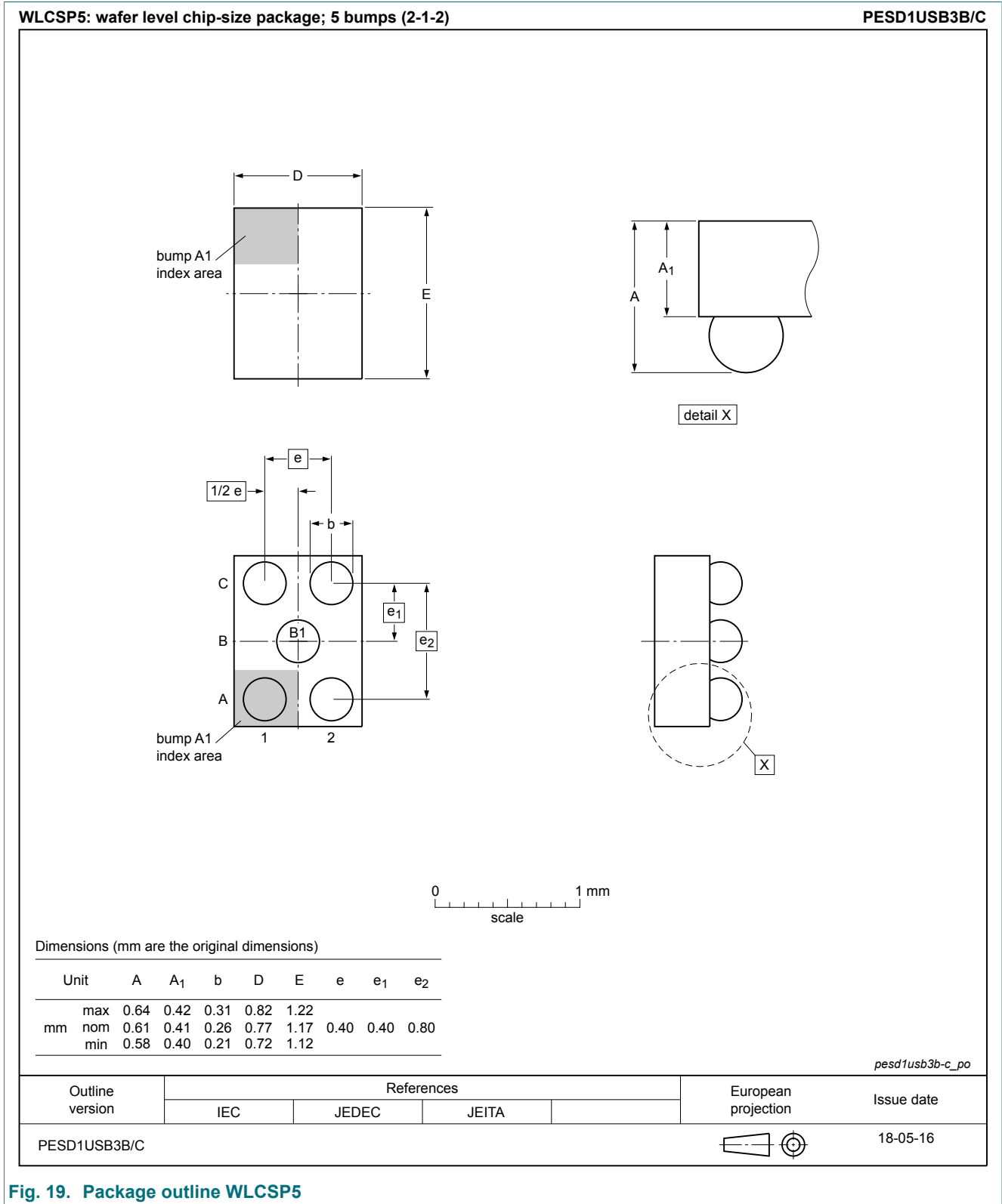
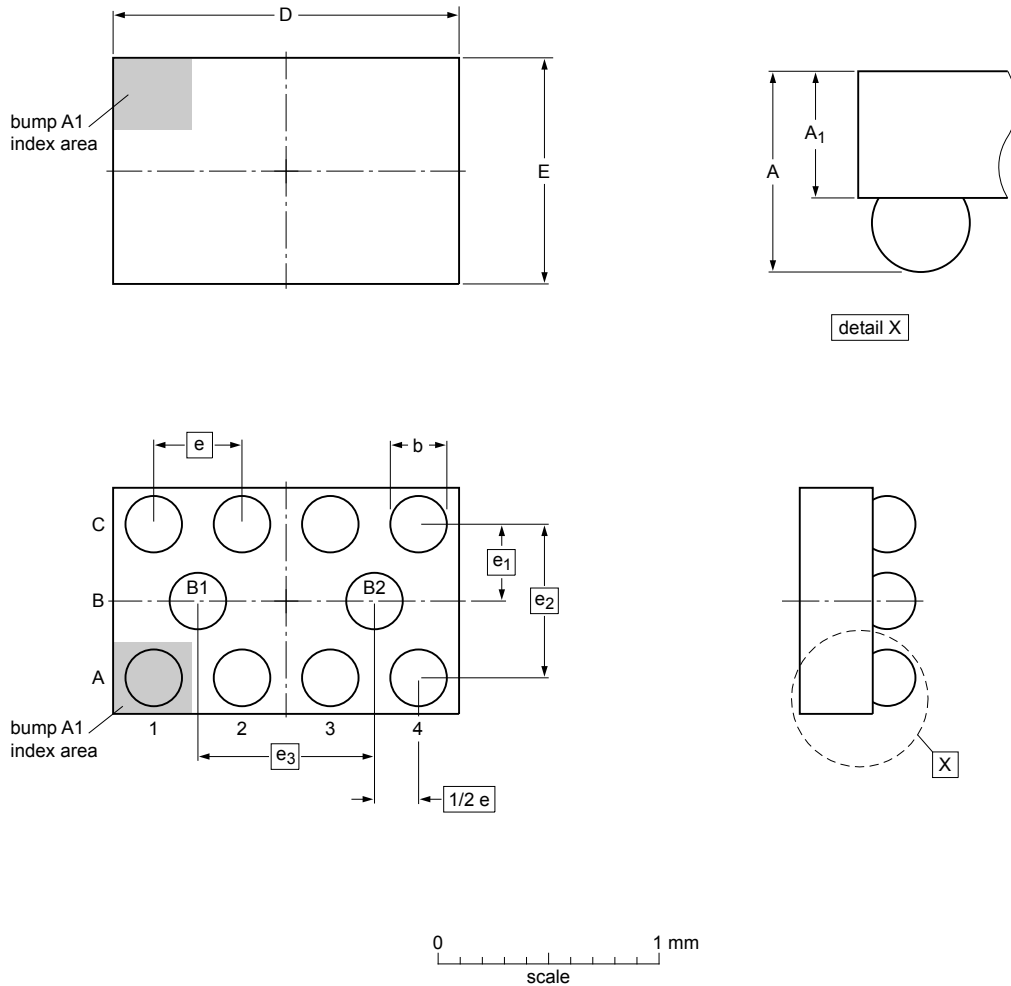


Fig. 19. Package outline WLCSP5

WLCSP10: wafer level chip-size package; 10 bumps (4-2-4)

PESD2USB3B/C



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	e <sub>3</sub>
mm	max 0.64	max 0.42	max 0.31	max 1.62	max 1.22	max 0.40	max 0.40	max 0.80	max 0.80
	nom 0.61	nom 0.41	nom 0.26	nom 1.57	nom 1.17	nom 0.40	nom 0.40	nom 0.80	nom 0.80
	min 0.58	min 0.40	min 0.21	min 1.52	min 1.12				

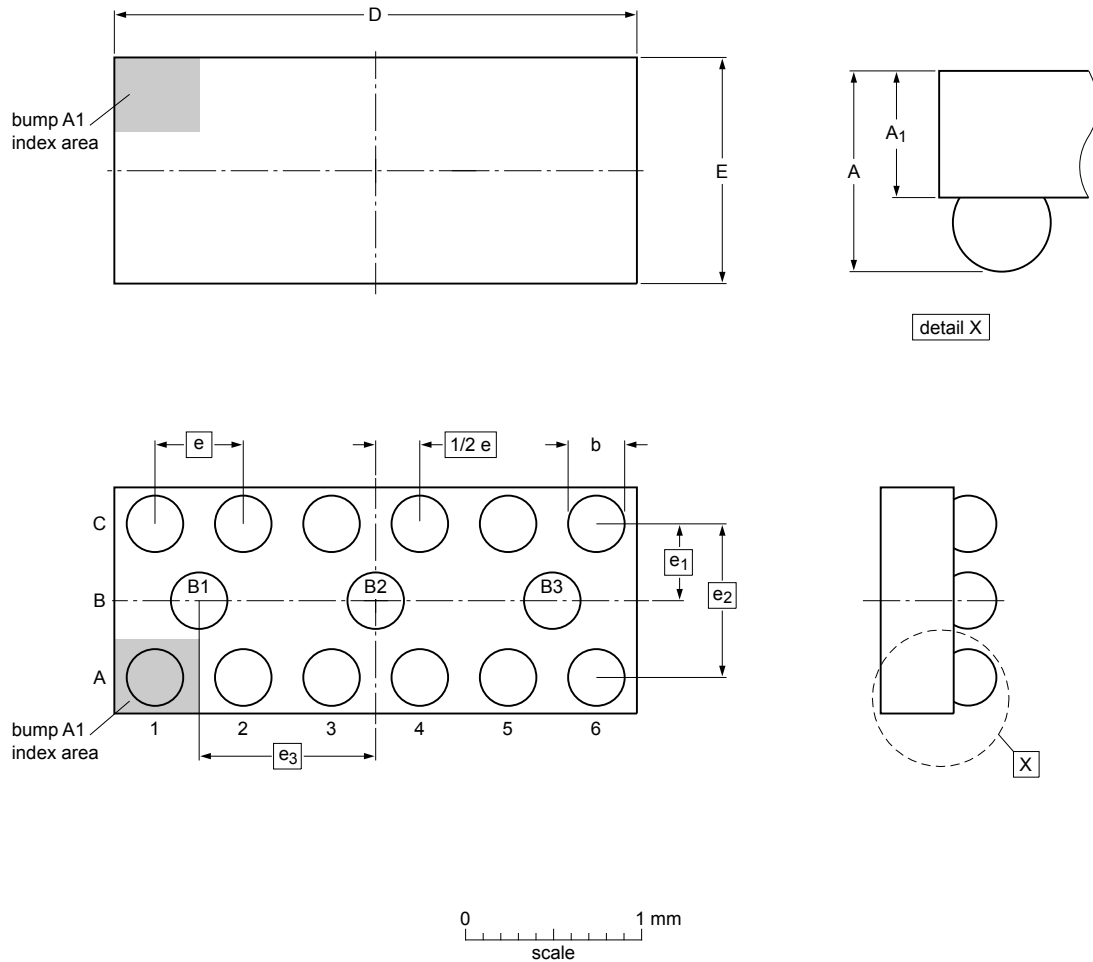
pesd2usb3b-c\_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
PESD2USB3B/C						18-05-16

Fig. 20. Package outline WLCSP10

WLCSP15: wafer level chip-size package; 15 bumps (6-3-6)

PESD3USB3B/C



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	e <sub>3</sub>
max	0.64	0.42	0.31	2.42	1.22				
mm nom	0.61	0.41	0.26	2.37	1.17	0.40	0.40	0.80	0.80
min	0.58	0.40	0.21	2.32	1.12				

pesd3usb3b-c\_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
PESD3USB3B/C						18-05-16

Fig. 21. Package outline WLCSP15

9. Soldering

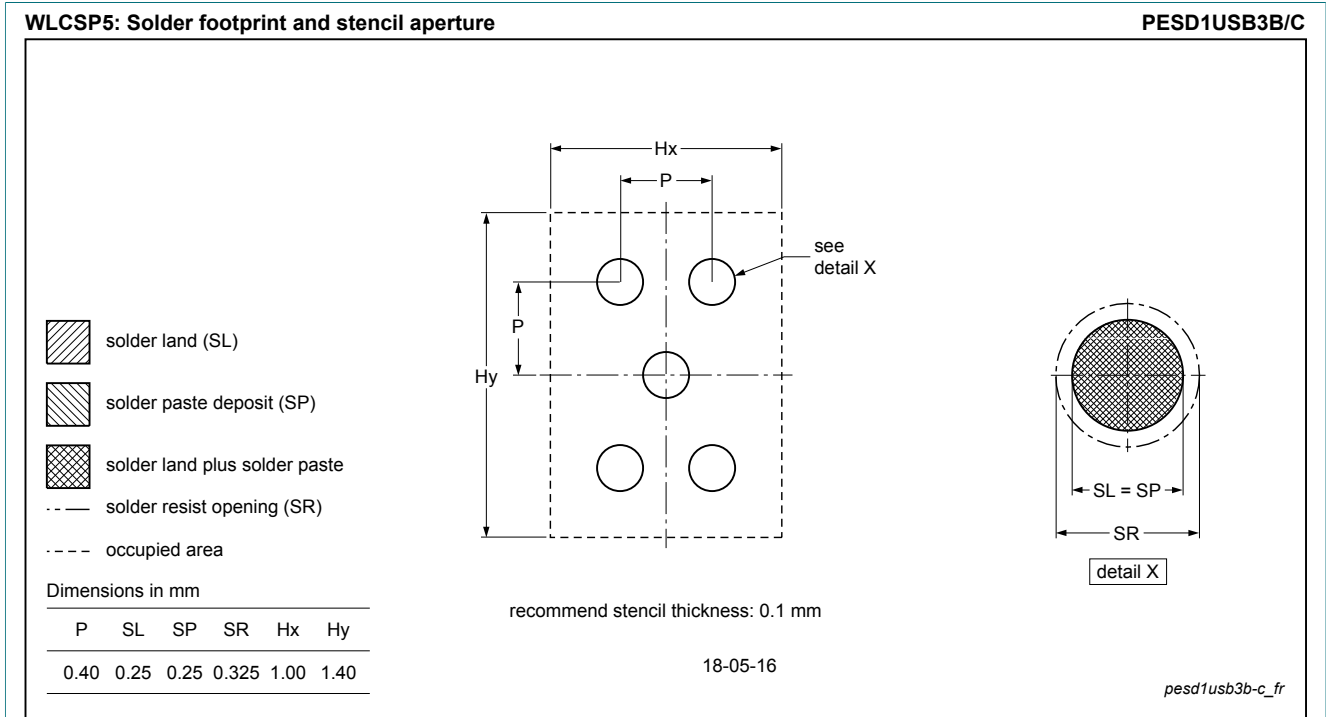


Fig. 22. Soldering footprint WLCSP5 (PESD1USB3B/C)

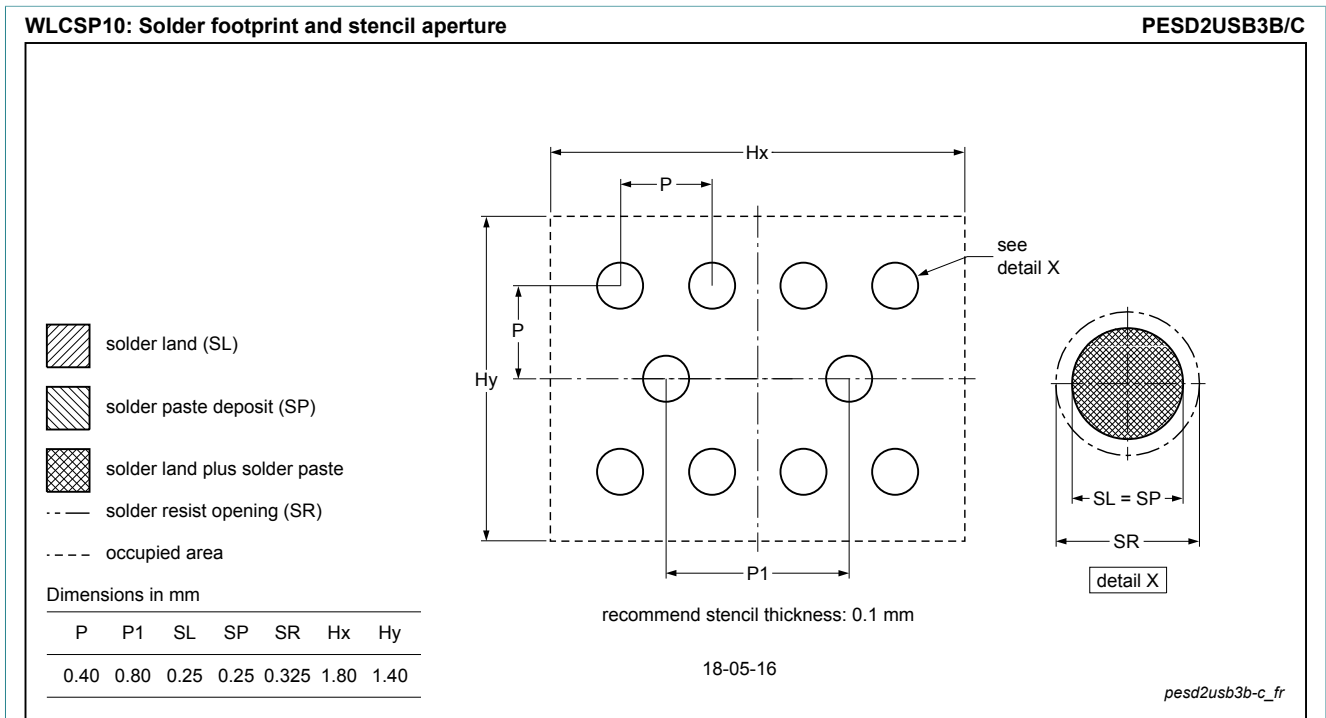
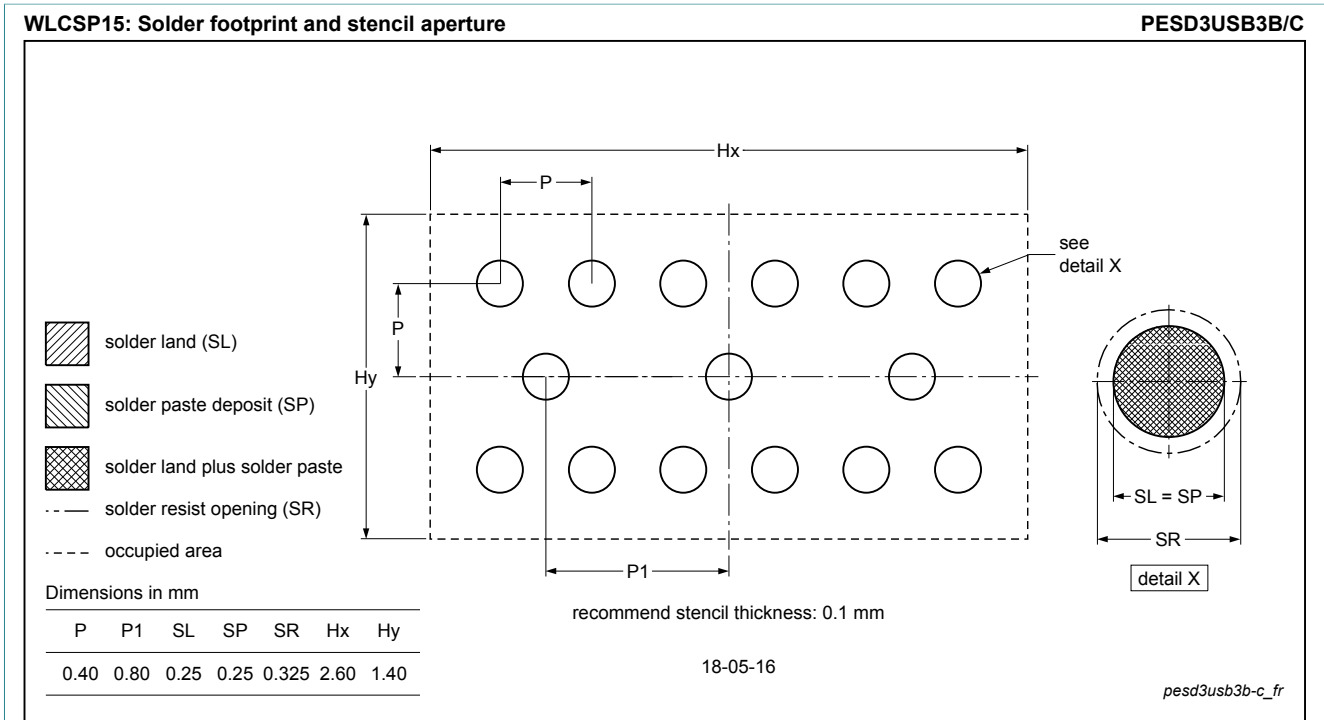


Fig. 23. Soldering footprint WLCSP10 (PESD2USB3B/C)



**Fig. 24. Soldering footprint WLCSP15 (PESD3USB3B/C)**

## 10. Revision history

**Table 8. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
PESDxUSB3B_C_SER v.2	20190129	Product data sheet	-	PESDxUSB3B_C_SER v.1
Modifications:	<ul style="list-style-type: none"><li>Limiting values: maximum value for <math>T_{amb}</math> updated</li><li>Frequency characteristics: Fig 2 removed and Fig 3 title adjusted</li></ul>			
PESDxUSB3B_C_SER v.1	20180706	Product data sheet	-	-



## 11. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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For more information, please visit: <http://www.nexperia.com>

For sales office addresses, please send an email to: [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)

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